## **TECHNICAL DATA SHEET**



# QLE 1051 1 Part Non-Corrosive Neutral Cure Adhesive Sealant and Potting Material (Electronic Grade)

#### Description

This is a one-component, self-bonding elastomer designed for use in semiconductor applications. The material has excellent adhesion to many substrates.

#### **Key Features**

- 100% solids
- Two hour cure time at 150°C/302°F
- · Fast cure at elevated temperatures
- Primerless adhesion to a variety of substrates

### Application

Semiconductor applications

#### **Use and Cure Information**

This material is a one-component, white, heat-cured silicone elastomer. The material should only be used on clean surfaces to maximize adhesion properties. In addition, some substrates may be difficult to bond to and some, such as galvanized metal, may cause cure inhibition. When this occurs, a primer can be used to eliminate this problem.

Revision Date 13 Oct 2021

Revision No 3

Download Date 02 May 2024

Property	Test Method	Value
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**Uncured Product** 

Cure Type Addition
Rheology Liquid
Self Bonding Yes
Specific Gravity 1.50
Viscosity Brookfield 14,500 cP

Cured Product 60 minutes at 150°C

Color White Elongation at Break ISO 37 100 %

Hardness Shore A ASTM D 2240-95 **75** 

Max Working Temp 204 °C / 399 °F Min Working Temp -55 °C / -67 °F

Tensile Strength ISO 37 6.21 N/mm2 / 900 psi

**Electrical Properties** 

Dielectric Constant ASTM D-150 **2.8**Dissipation Factor ASTM D-150 **0.017** 

Volume Resistivity (Ohms ASTM D-257 **7E+14 ohms cm** 

Storage

Max Storage Temperature  $4.4 \, ^{\circ}\text{C} \, / \, 40 \, ^{\circ}\text{F}$  Shelf Life  $12 \, \text{mths}$